

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. Canceled
2. (previously presented): An assembly as claimed in claim 12, wherein said resin layer is photosensitive and thermosetting.
3. (currently amended): An assembly as claimed in claim 2, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer ~~would effect~~ effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.
4. (original): An assembly as claimed in claim 2, wherein said resin layer has a function for flip chip bonding and a function for passivation.
5. (currently amended): An assembly as claimed in claim 4, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit

surfaces of said electronic devices where resin forming said resin layer ~~would effect~~ effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

6. (currently amended): An assembly as claimed in claim 12, wherein said resin layer has a function for flip chip bonding and a function for passivation.

7. (currently amended): An assembly as claimed in claim 6, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer ~~would effect~~ effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

8. (currently amended): An assembly as claimed in claim 12, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer ~~would effect~~ effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

9. (withdrawn): In a method of connecting at least two electronic devices included in an assembly in which a plurality of electronic devices of different kinds are connected to a single electronic device, said electronic devices are connected to each other by conductive

portions implemented by metal, but insulated from each other by insulating portions implemented by an adhesive, sealable patterned resin layer, said method comprising a step of subjecting said adhesive, sealable resin and electrodes to thermocompression at the same time.

10. (withdrawn): In a method of connecting at least two electronic devices included in an assembly in which a plurality of electronic devices of different kinds are connected to a single electronic device, said electronic devices are connected to each other by conductive portions implemented by metal, but insulated from each other by insulating portions implemented by an adhesive, sealable patterned resin layer, said method comprising a first step of connecting said conductive portions by applying an ultrasonic wave while holding bumps and electrode pads aligned with said bumps in contact with each other, and a second of connecting a resin layer formed on any one of said electronic devices and a contact surface formed on a function element corresponding to said resin layer by thermocompression, said second step being executed after or simultaneously with said first step.

11. (withdrawn): In a method of constructing an assembly in which a plurality of electronic devices of different kinds are connected to a single electronic device, said electronic devices are connected to each other by conductive portions implemented by metal, but insulated from each other by insulating portions implemented by an adhesive, sealable and patterned resin layer, said method comprising a step of connecting at least two of said electronic devices via thermosetting, sealable resin layer while maintaining, on a passive device mounted on any one of said electronic devices or on a circuit surface of the electronic device, a temperature of portions

where resin constituting said resin layer would effect a device characteristic higher than a temperature of the other portions.

12. (currently amended): An assembly of a plurality of electronic devices,

comprising:

a first electronic device connected to other electronic devices by conductive portions formed of metal, but insulated from said other electronic devices by insulating portions that comprise an adhesive, sealable, patterned resin layer;

a second electronic device connected to said first electronic device; and

a third electronic device positioned between said first electronic device and said second electronic device and connected to said second electronic device,

wherein the first, second and third electronic devices are stacked in the direction of height.